

BEST AVAILABLE COPY

LIGHT-EMITTING DIODE

Patent Number: JP6069546
Publication date: 1994-03-11
Inventor(s): GOTOU HIROMASA; others: 01
Applicant(s): ASAHI CHEM IND CO LTD
Requested Patent: ☐ JP6069546
Application Number: JP19920222627 19920821
Priority Number(s):
IPC Classification: H01L33/00
EC Classification:
Equivalents:

Abstract

PURPOSE: To obtain an LED provided with a good light-emitting characteristic by using a wire bonding method when all electrodes for an element chip using an insulating substrate are connected to individual lead members.

CONSTITUTION: Individual chips are cut by using a dicing saw, one chip is taken out, the side of a reflection film 32 is die-bonded to a lead member 43 by using a Pb-Sn solder, electrodes for an n-type GaN layer 30 and an n-type Ga_{0.8}In_{0.2}N layer 41 are connected by 30μm φ Au wires 35 by using a wire bonding apparatus. Then, an i-type GaN layer electrode 27 is connected to a lead member 44 and an i-type Ga_{0.8}In_{0.2}N layer electrode 38 is connected to a lead member 43 respectively by 30μm φ Au wires 35 by using the wire bonding apparatus, and a manufactured light-emitting element 46 is sealed with a transparent epoxy resin. Consequently, all electrodes formed inside the same plane can be connected individually to lead members divided into the same number as the number of electrodes by using a wire bonding method. Thereby, an LED whose performance is stable can be supplied.

Data supplied from the esp@cenet database - 12